

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **HARA, Shoji et al.**

Serial No.: 09/782,169

Filed: February 14, 2001



Group Art Unit: 1762

Examiner: **Brian K. Talbot**

P.T.O. Confirmation No.: 2107

For: **Laminate Comprising Polyimide and Conductor Layer, Multi-Layer Wiring Board with the Use of the Same and Process for Producing the Same**

AMENDMENT

Commissioner for Patents  
Washington, D.C. 20231

**RECEIVED**  
JUL 2 2002  
TC 1700  
June 21, 2002

Sir:

In response to the Office Action dated **February 21, 2002**, please amend the above-identified application as follows:

IN THE SPECIFICATION:

**Please amend the specification as follows:**